

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A ~~high-frequency~~ power amplifier comprising:
a multilayer substrate including a plurality of laminated dielectric layers;
a wiring prohibited area located on at least one of an obverse side and a reverse side of said multilayer substrate in which wiring is prohibited;
a first strip conductor located within said multilayer substrate;
a second strip conductor located within said multilayer substrate at a position, in a lamination direction of said multilayer substrate, different from that of said first strip conductor;
a via electrically connecting said first strip conductor to said second strip conductor;
and
a first grounding conductor and a second grounding conductor disposed sequentially in the lamination direction of said multilayer substrate and sandwiching said first strip conductor and said second strip conductor, wherein ~~at least one of said first grounding conductor and said second grounding conductor~~ includes:
a first grounding conductor portion ~~for~~ located in said wiring prohibited area;
and
a second grounding conductor portion ~~for~~ located in an area other than said wiring prohibited area so that said second grounding conductor portion is positioned, ~~in~~ with respect to the lamination direction of said multilayer substrate, at a position different from said first grounding conductor portion.

2. (Currently Amended) The ~~high-frequency~~ power amplifier according to claim 1, wherein said wiring prohibited area includes:
a first wiring prohibited area located on the obverse side of said multilayer substrate;
and
a second wiring prohibited area located on the reverse side of said multilayer substrate, said second wiring prohibited area overlapping said first wiring prohibited area, when viewed in the lamination direction of said multilayer substrate, wherein length of said first wiring prohibited area in said lamination direction of said multilayer substrate is different from that of said second wiring prohibited area.

3. (Currently Amended) The ~~high-frequency~~ power amplifier according to claim 1, wherein said wiring prohibited area includes:
a first wiring prohibited area located on the obverse side of said multilayer substrate;
and

a second wiring prohibited area located on the reverse side of said multilayer substrate, said second wiring prohibited area not overlapping said first wiring prohibited area, when viewed in the lamination direction of said multilayer substrate.

4. (Currently Amended) The ~~high-frequency~~ power amplifier according to claim 1, wherein one end of said first grounding conductor portion runs along a periphery of said via, when viewed in the lamination direction of said multilayer substrate.

5. (Currently Amended) A ~~high-frequency~~ power amplifier comprising:
a multilayer substrate including a plurality of laminated dielectric layers;
a first wiring prohibited area located on an obverse side of said multilayer substrate;
a second wiring prohibited area located on a reverse side of said multilayer substrate, said second wiring prohibited area overlapping said first wiring prohibited area, when viewed in a lamination direction of said multilayer substrate;
a strip conductor disposed within said multilayer substrate; and
a first grounding conductor and a second grounding conductor disposed sequentially in the lamination direction of said multilayer substrate and sandwiching said strip conductor, wherein

length of said first wiring prohibited area in the lamination direction of said multilayer substrate is equal to that of said second wiring prohibited area, and

said first grounding conductor includes:

a first grounding conductor portion for said first wiring prohibited area
and

a second grounding conductor portion for an area on the obverse side of said multilayer substrate such that said second grounding conductor portion is positioned, in the lamination direction of said multilayer substrate, different from said first grounding conductor portion, the area being outside said first wiring prohibited area; and

said second grounding conductor includes:

a third grounding conductor portion for said second wiring prohibited area; and

a fourth grounding conductor portion for an area on the reverse side of said multilayer substrate such that said fourth grounding conductor portion is positioned, in the lamination direction of said multilayer substrate, different from said third grounding conductor portion, the area being outside said second wiring prohibited area.

6. (New) The power amplifier according to claim 1, wherein said second grounding conductor includes:

- a third grounding conductor portion located in said wiring prohibited area; and
- a fourth grounding conductor portion located in an area other than said wiring prohibited area so that said fourth grounding conductor portion is positioned, with respect to the lamination direction of said multilayer substrate, at a position different from said third grounding conductor portion.

This listing of claims replaces all prior versions, and listings, of claims in the application.